

CMOS STATIC RAM 1 MEG (128K x 8-BIT)

IDT71024

FEATURES:

- 128K x 8 advanced high-speed CMOS static RAM
- Commercial (0° to 70°C), Industrial (-40° to 85°C) and Military (-55° to 125°C) temperature options
- Equal access and cycle times
 - Military: 15/17/20/25nsIndustrial: 15/20ns
 - Commercial: 12/15/17/20ns
- Two Chip Selects plus one Output Enable pin
- · Bidirectional inputs and outputs directly TTL-compatible
- · Low power consumption via chip deselect
- Available in 300 and 400 mil Plastic SOJ, and LCC packages
- Military product compliant to MIL-STD-883, Class B

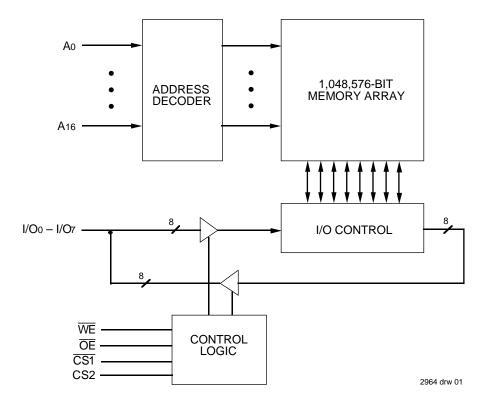
DESCRIPTION:

The IDT71024 is a 1,048,576-bit high-speed static RAM organized as 128K x 8. It is fabricated using IDT's high-performance, high-reliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a cost-effective solution for high-speed memory needs.

The IDT71024 has an output enable pin which operates as fast as 6ns, with address access times as fast as 12ns available. All bidirectional inputs and outputs of the IDT71024 are TTL-compatible and operation is from a single 5V supply. Fully static asynchronous circuitry is used; no clocks or refreshes are required for operation.

The IDT71024 is packaged in 32-pin 300 mil Plastic SOJ, 32-pin 400 mil Plastic SOJ, and 32-pin 400 x 820 mil LCC packages.

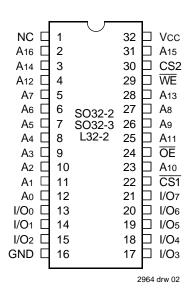
FUNCTIONAL BLOCK DIAGRAM



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MAY 1997

PIN CONFIGURATION



SOJ/LCC TOP VIEW

ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Rating	Com'l, Ind'l	Mil.	Unit
VTERM ⁽²⁾	Terminal Voltage Relative to GND	-0.5 to +7.0	-0.5 to +7.0	>
TBIAS	Temperature Under Bias	-55 to +125	-65 to +135	ô
Tstg	Storage Temperature	-55 to +125	-65 to +150	°C
Рт	Power Dissipation	1.25	1.25	W
lout	DC Output Current	50	50	mA

NOTES:

2964 tbl 02

- Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
- 2. VTERM must not exceed Vcc + 0.5V.

TRUTH TABLE(1,2)

INPUTS					
WE	CS1	CS2	ŌĒ	I/O	FUNCTION
Χ	Н	Χ	Χ	High-Z	Deselected-Standby (ISB)
Х	VHC ⁽³⁾	Χ	Χ	High-Z	Deselected-Standby (ISB1)
Х	Х	L	Х	High-Z	Deselected-Standby (ISB)
Х	Х	VLC ⁽³⁾	Х	High-Z	Deselected-Standby (ISB1)
Н	L	Н	Н	High-Z	Outputs Disabled
Н	L	Н	L	DATAOUT	Read Data
L	L	Η	Х	DATAIN	Write Data

NOTES:

2964 tbl 01

- 1. $H = V_{IH}$, $L = V_{IL}$, X = Don't care.
- 2. VLC = 0.2V, VHC = VCC -0.2V.
- 3. Other inputs \geq VHC or \leq VLC.

RECOMMENDED OPERATING TEMPERATURE AND SUPPLY VOLTAGE

Grade Temperature		GND	Vcc
Commercial	0°C to +70°C	0V	$5.0V \pm 0.5V$
Industrial	-40°C to +85°C	0V	$5.0V \pm 0.5V$
Military	-55°C to +125°C	0V	$5.0V \pm 0.5V$

2964 tbl 03

RECOMMENDED DC OPERATING CONDITIONS

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
VIH	Input High Voltage	2.2	_	Vcc+0.5	V
VIL	Input Low Voltage	$-0.5^{(1)}$	_	0.8	V

NOTE:

2964 tbl 04

1. V_{IL} (min.) = -1.5V for pulse width less than 10ns, once per cycle.

DC ELECTRICAL CHARACTERISTICS

 $VCC = 5.0V \pm 10\%$

			IDT71024		
Symbol	Parameter	Test Condition	Min.	Max.	Unit
ILI	Input Leakage Current	Vcc = Max., Vin = GND to Vcc	_	5	μΑ
ILO	Output Leakage Current	Vcc = Max., $\overline{\text{CS1}}$ = ViH, CS2 = ViL, Vout = GND to Vcc	_	5	μΑ
Vol	Output LOW Voltage	IOL = 8mA, Vcc = Min.	_	0.4	V
Voн	Output HIGH Voltage	Iон = -4mA, Vcc = Min.	2.4	_	V

2964 tbl 05

DC ELECTRICAL CHARACTERISTICS(1)

 $(VCC = 5.0V \pm 10\%, VLC = 0.2V, VHC = VCC - 0.2V)$

		71024S12		024S12 71024S15		71024\$17		71024S20		71024\$25		
Symbol	Parameter	Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	Com'l.	Mil.	Unit
Icc	Dynamic Operating Current, $CS2 \ge V_{IH}$ and $CS2 \ge V_{IH}$ and $\overline{CS1} \le V_{IL}$, Outputs Open, $VCC = Max.$, $f = f_{MAX}^{(2)}$	160		155	180	150	170	140	160	_	145	mA
ISB		35	_	35	40	35	40	35	40	_	35	mA
ISB1	Full Standby Power Supply Current (CMOS Level) $\overline{CS1} \ge VHC$, or CS2 $\le VLC$ Outputs Open, $VCC = Max.$, $f = 0^{(2)}$, $VIN \le VLC$ or $VIN \ge VHC$	10	_	10	15	10	15	10	15	_	15	mA

NOTES:

2964 tbl 06

DC ELECTRICAL CHARACTERISTICS(1)

 $(VCC = 5.0V \pm 10\%, V_{LC} = 0.2V, V_{HC} = V_{CC} - 0.2V)$

		71024S15	71024S20	
Symbol	Parameter	Industrial	Industrial	Unit
Icc	Dynamic Operating Current, $CS2 \ge VIH$ and $CS2 \ge VIH$ and $CS2 \ge VIH$ and $CS1 \le VIL$, Outputs Open, $VCC = Max.$, $f = fMAX^{(2)}$	180	160	mA
ISB	Standby Power Supply Current (TTL Level) $\overline{\text{CS1}} \ge \text{VIH or CS2} \le \text{VIL, Outputs Open,}$ $\text{VCC} = \text{Max., } f = \text{fMAX}^{(2)}$	45	45	mA
ISB1	Full Standby Power Supply Current (CMOS Level) $\overline{CS1} \ge VHC$, or $CS2 \le VLC$ Outputs Open, $VCC = Max.$, $f = 0^{(2)}$, $VIN \le VLC$ or $VIN \ge VHC$	15	15	mA

NOTES:

2964 tbl 07

CAPACITANCE

 $(TA = +25^{\circ}C, f = 1.0MHz, SOJ package)$

Symbol	Parameter ⁽¹⁾	Conditions	Max.	Unit
CIN	Input Capacitance	VIN = 3dV	7	pF
CI/O	I/O Capacitance	Vout = 3dV	8	pF

NOTE

2964 tbl 08

 This parameter is guaranteed by device characterization, but is not production tested.

^{1.} All values are maximum guaranteed values.

^{2.} fMAX = 1/tRC (all address inputs are cycling at fMAX); f = 0 means no address input lines are changing.

^{1.} All values are maximum guaranteed values.

^{2.} fMAX = 1/trc (all address inputs are cycling at fMAX); f = 0 means no address input lines are changing.

AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	See Figures 1 and 2

2964 tbl 09

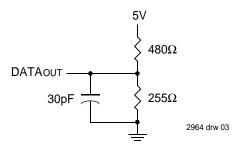
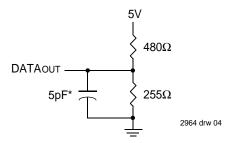


Figure 1. AC Test Load



*Including jig and scope capacitance.

Figure 2. AC Test Load (for tclz, tolz, tchz, tohz, tow, and twhz)

AC ELECTRICAL CHARACTERISTICS (Vcc = 5.0V ± 10%, All Temperature Ranges)

		71024	S12 ⁽¹⁾	7102	4S15	71024	S17 ⁽³⁾	71024	4S20	71024	S25 ⁽²⁾	
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit
Read Cy	cle											
trc	Read Cycle Time	12	_	15	_	17	_	20	_	25	_	ns
tAA	Address Access Time	_	12	_	15	_	17	_	20	_	25	ns
tacs	Chip Select Access Time	_	12	_	15	_	17	_	20	_	25	ns
tcLZ ⁽⁴⁾	Chip Select to Output in Low-Z	3	_	3	_	3	_	3	_	3	_	ns
tcHZ ⁽⁴⁾	Chip Deselect to Output in High-Z	0	6	0	7	0	8	0	8	0	10	ns
toe	Output Enable to Output Valid	_	6	_	7	_	8	_	8	_	10	ns
tolz ⁽⁴⁾	Output Enable to Output in Low-Z	0	_	0	_	0	_	0	_	0	_	ns
toHZ ⁽⁴⁾	Output Disable to Output in High-Z	0	5	0	5	0	6	0	7	0	10	ns
tон	Output Hold from Address Change	4	_	4	_	4	_	4	_	4	_	ns
tpu ⁽⁴⁾	Chip Select to Power-Up Time	0	_	0	_	0	_	0	_	0	_	ns
tPD ⁽⁴⁾	Chip Deselect to Power-Down Time	_	12	_	15	_	17	_	20	_	25	ns
Write Cy	cle											
twc	Write Cycle Time	12	_	15	_	17	_	20	_	25	_	ns
taw	Address Valid to End-of-Write	10	_	12		13	_	15	_	15	_	ns
tcw	Chip Select to End-of-Write	10	_	12	_	13	_	15	_	15	_	ns
tas	Address Set-up Time	0	_	0	_	0	_	0	_	0	_	ns
twp	Write Pulse Width	10	_	12	_	13	_	15	_	15	_	ns
twr	Write Recovery Time	0	_	0	1	0		0	_	0	_	ns
tow	Data Valid to End-of-Write	7	_	8	_	9	_	9	_	10	_	ns
tDH	Data Hold Time	0	_	0	_	0	_	0	_	0	_	ns
tow ⁽⁴⁾	Output Active from End-of-Write	3	_	3	_	3	_	4	_	4	_	ns
twhz ⁽⁴⁾	Write Enable to Output in High-Z	0	5	0	5	0	7	0	8	0	9	ns

NOTES:

1. 0° C to +70°C temperature range only.

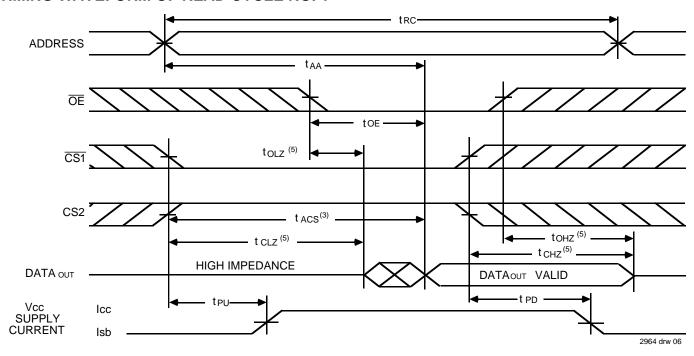
2964 tbl 010

^{2. -55°}C to +125°C temperature range only.

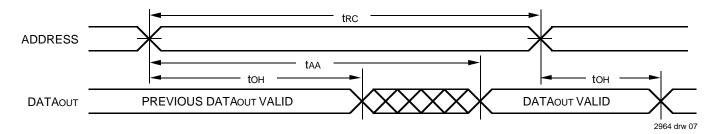
^{3.} 0° C to +70°C and -55°C to +125°C temperature ranges only.

^{4.} This parameter guaranteed with the AC load (Figure 2) by device characterization, but is not production tested.

TIMING WAVEFORM OF READ CYCLE NO. 1⁽¹⁾



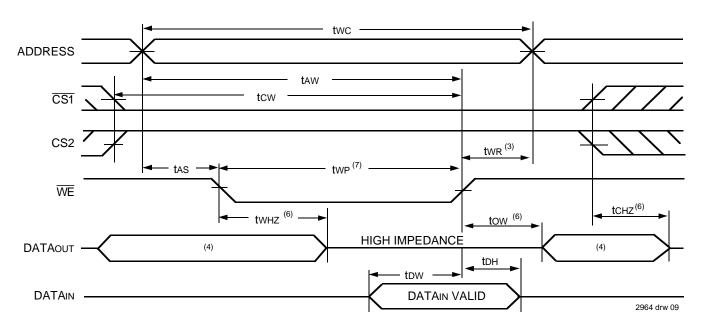
TIMING WAVEFORM OF READ CYCLE NO. 2^(1, 2, 4)



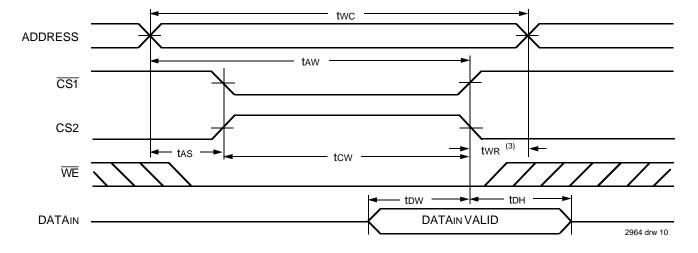
NOTES:

- 1. WE is HIGH for Read Cycle.
- 2. Device is continuously selected, $\overline{\text{CS1}}$ is LOW, CS2 is HIGH.
- 3. Address must be valid prior to or coincident with the later of $\overline{\text{CS1}}$ transition LOW and CS2 transition HIGH; otherwise tAA is the limiting parameter.
- 4. $\overline{\mathsf{OF}}$ is LOW
- 5. Transition is measured ±200mV from steady state.

TIMING WAVEFORM OF WRITE CYCLE NO. 1 ($\overline{\text{WE}}$ CONTROLLED TIMING) $^{(1, 2, 5, 7)}$



TIMING WAVEFORM OF WRITE CYCLE NO. 2 ($\overline{\text{CS1}}$ AND CS2 CONTROLLED TIMING) $^{(1,\,2,\,5)}$



NOTES

- 1. WE must be HIGH, CS1 must be HIGH, or CS2 must be LOW during all address transitions.
- 2. A write occurs during the overlap of a LOW $\overline{\text{CS1}}$, HIGH CS2, and a LOW $\overline{\text{WE}}$.
- 3. twn is measured from the earlier of either CS1 or WE going HIGH or CS2 going LOW to the end of the write cycle.
- 4. During this period, I/O pins are in the output state, and input signals must not be applied.
- 5. If the CS1 LOW transition or the CS2 HIGH transition occurs simultaneously with or after the WE LOW transition, the outputs remain in a high impedance state. CS1 and CS2 must both be active during the tcw write period.
- 6. Transition is measured ±200mV from steady state.
- 7. \overline{OE} is continuously HIGH. During a \overline{WE} controlled write cycle with \overline{OE} LOW, twp must be greater than or equal to twHz + tbw to allow the I/O drivers to turn off and data to be placed on the bus for the required tbw. If \overline{OE} is HIGH during a \overline{WE} controlled write cycle, this requirement does not apply and the minimum write pulse is the specified twp.

ORDERING INFORMATION

